

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

Claims 1-35 (canceled).

Claim 36 (currently amended): A device transfer method comprising:  
embedding a plurality of first devices into a pressure sensitive adhesive layer provided on a first substrate such that the plurality of first devices penetrate the surface of the pressure sensitive adhesive layer, the entire pressure sensitive adhesive layer being in an uncured state;  
forming a temporary adhesion layer on a surface of a second substrate, and arranging a plurality of second devices on the temporary adhesion layer;  
embedding ~~a-the~~ plurality of second devices ~~arranged on a second substrate~~ into the pressure sensitive adhesive layer provided on the first substrate by positioning the first and second substrates in close proximity thereof such that the temporary adhesion layer comes into contact with the pressure sensitive adhesive layer and the plurality of second devices ~~arranged on the second substrate~~ ~~penetrate the surface of~~ are entirely embedded within the pressure sensitive adhesive layer such that the plurality of second devices become substantially flush with the surface of the pressure sensitive adhesive layer; and  
stripping the plurality of second devices from the second substrate while the entire pressure sensitive adhesive layer remains in an uncured state thereby holding both the plurality of first and second devices in an embedded state within the pressure sensitive adhesive layer, wherein the first devices and second devices are light emitting diodes having different characteristics.

Claim 37 (canceled).

Claim 38 (previously presented): The device transfer method as set forth in claim 36, wherein the plurality of first devices and the plurality of second devices are held in the embedded state in different areas on the first substrate.

Claim 39 (currently amended): A method of manufacturing a display apparatus comprising:

forming a temporary adhesion layer on a surface of a first substrate, and arranging a plurality of devices on the temporary adhesion layer;

embedding the devices arranged on a first substrate into a pressure sensitive adhesive layer provided on a second substrate by positioning the first and second substrates in close proximity thereof such that the temporary adhesion layer comes into contact with the pressure sensitive adhesive layer and the devices arranged on the first substrate penetrate the surface of are entirely embedded within the pressure sensitive adhesive layer such that the plurality of second devices become substantially flush with the surface of the pressure sensitive adhesive layer, wherein the entire pressure sensitive adhesive layer is in an uncured state and the devices are light emitting diodes;

stripping the devices from the first substrate while the entire pressure sensitive adhesive layer remains in an uncured state thereby holding the devices in an embedded and uncured state within the pressure sensitive adhesive layer,

hardening the pressure sensitive adhesive layer to cure the pressure sensitive adhesive layer;

forming first electric wirings on the pressure sensitive adhesive layer, adhering a third substrate onto a side on which the first electric wirings are formed of the pressure sensitive adhesive layer, and stripping the second substrate and the pressure sensitive adhesive layer from each other; and

providing the pressure sensitive adhesive layer with openings reaching the devices, filling the openings with a conductive material, and forming second electric wirings on the pressure sensitive adhesive layer.

Claim 40 (previously presented): The method of manufacturing a display apparatus as set forth in claim 39, wherein display is carried out through simple matrix driving by impressing a voltage on the devices through the first electric wirings and the second electric wirings.

Claim 41 (currently amended): A method of manufacturing a display apparatus comprising:

forming a temporary adhesion layer on a surface of a first substrate, and arranging a plurality of devices on the temporary adhesion layer;

embedding ~~a~~the plurality of first devices arranged on a first substrate into a pressure sensitive adhesive layer provided on a second substrate by positioning the first and second substrates in close proximity thereof such that the temporary adhesion layer comes into contact with the pressure sensitive adhesive layer and the plurality of first devices arranged on the first substrate penetrate the surface of are entirely embedded within the pressure sensitive adhesive layer such that the plurality of second devices become substantially flush with the surface of the pressure sensitive adhesive layer, the entire pressure sensitive adhesive layer being in an uncured state;

stripping the plurality of first devices from the first substrate while the entire pressure sensitive adhesive layer remains in an uncured state thereby holding the plurality of first devices in an embedded and uncured state within the pressure sensitive adhesive layer;

further embedding a plurality of second devices arranged on the first substrate into the pressure sensitive adhesive layer by positioning the first and second substrates in close proximity thereof such that the plurality of second devices arranged on the first substrate penetrate the surface of the pressure sensitive adhesive layer;

stripping the plurality of second devices from the first substrate while the entire pressure sensitive adhesive layer remains in an uncured state thereby holding the plurality of second devices in an embedded and uncured state within the pressure sensitive adhesive layer, where the plurality of first devices are embedded in the pressure sensitive adhesive layer;

hardening the pressure sensitive adhesive layer to cure the pressure sensitive adhesive layer where the plurality of first devices and the plurality of second devices are held in an embedded and cured state within the pressure sensitive adhesive layer;

forming first electric wirings on the pressure sensitive adhesive layer, adhering a third substrate onto the side on which the first electric wirings are formed of the pressure sensitive layer, and stripping the second substrate and the pressure sensitive adhesive layer from each other; and

providing the pressure sensitive adhesive layer with openings reaching the plurality of first devices or the plurality of second devices, filling the openings with a conductive material, and forming second electric wirings on the pressure sensitive adhesive layer, wherein the first devices and second devices are light emitting diodes.

Claim 42 (previously presented): The method of manufacturing a display apparatus as set forth in claim 41, wherein the first devices and the second devices have different characteristics.

Claim 43 (previously presented): The method of manufacturing a display apparatus as set forth in claim 41, wherein the plurality of first devices and the plurality of second devices are held in the embedded state in different areas on the second substrate.

Claim 44 (previously presented): The method of manufacturing a display apparatus as set forth in claim 41, wherein display is carried out through simple matrix driving by impressing a voltage on the plurality of first devices or the plurality of second devices through the first electric wirings and the second electric wirings.

Claim 45 (previously presented): The method of manufacturing a display apparatus as set forth in claim 41, wherein any one of the plurality of first devices and the plurality of second devices are any one of display devices and driving circuit devices.

Claim 46 (previously presented): The method of manufacturing a display apparatus as set forth in claim 45, wherein display is carried out through active matrix driving by impressing a voltage on the display devices by the driving circuit devices.

Claim 47 (previously presented): The device transfer method as set forth in claim 36, further comprising bringing the plurality of second devices into contact with a temporary adhesion layer provided on the second substrate for temporarily adhering the devices to the temporary adhesion layer thereby arranging the devices on the second substrate, before

embedding the plurality of second devices into the uncured pressure sensitive adhesive layer provided on the first substrate.

Claim 48 (previously presented): The device transfer method as set forth in claim 47, wherein a tack of the pressure sensitive adhesive layer provided on the first substrate is greater than a tack of the temporary adhesion layer provided on the second substrate.

Claim 49 (previously presented): The device transfer method as set forth in claim 48, wherein the tack of at least one of the pressure sensitive adhesive layer and the temporary adhesion layer is changed so that the tack of the pressure sensitive adhesive layer will be greater than the tack of the temporary adhesion layer.

Claim 50 (previously presented): The device transfer method as set forth in claim 36, further comprising curing the pressure sensitive adhesive layer using a heating treatment.

Claim 51 (previously presented): The method of manufacturing a display apparatus of claim 39, wherein the pressure sensitive adhesive layer is hardened after stripping the devices from the first substrate.